

FDP7042L / FDB7042L

N-Channel Logic Level PowerTrench® MOSFET

General Description

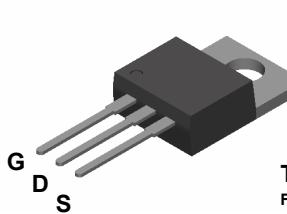
This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for "low side" synchronous rectifier operation, providing an extremely low $R_{DS(ON)}$.

Applications

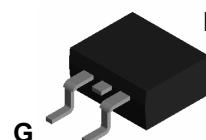
- Synchronous rectifier
- DC/DC converter

Features

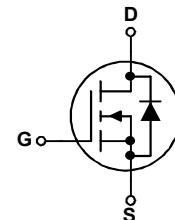
- 50 A, 30 V. $R_{DS(ON)} = 9 \text{ m}\Omega @ V_{GS} = 4.5 \text{ V}$
 $R_{DS(ON)} = 7.5 \text{ m}\Omega @ V_{GS} = 10 \text{ V}$
- Critical DC electrical parameters specified at elevated temperature
- High performance trench technology for extremely low $R_{DS(ON)}$
- 175°C maximum junction temperature rating



TO-220
FDP Series



TO-263AB
FDB Series



Absolute Maximum Ratings

$T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain-Source Voltage	30	V
V_{GSS}	Gate-Source Voltage	± 12	V
I_D	Drain Current – Continuous (Note 1)	50	A
	– Pulsed (Note 1)	150	
P_D	Total Power Dissipation @ $T_C = 25^\circ\text{C}$	83	W
	Derate above 25°C	0.48	W°C
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-65 to +175	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.8	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
FDB7042L	FDB7042L	13"	24mm	800 units
FDP7042L	FDP7042L	Tube	n/a	45

Electrical Characteristics

$T_A = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain–Source Breakdown Voltage	$V_{GS} = 0 \text{ V}$, $I_D = 250 \mu\text{A}$	30			V
ΔBV_{DSS} ΔT_J	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C		24		$\text{mV}/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24 \text{ V}$, $V_{GS} = 0 \text{ V}$			1	μA
I_{GSSF}	Gate–Body Leakage, Forward	$V_{GS} = 12 \text{ V}$, $V_{DS} = 0 \text{ V}$			100	nA
I_{GSSR}	Gate–Body Leakage, Reverse	$V_{GS} = -12 \text{ V}$, $V_{DS} = 0 \text{ V}$			-100	nA
On Characteristics (Note 2)						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$	0.8	1.2	2	V
$\Delta V_{GS(\text{th})}$ ΔT_J	Gate Threshold Voltage Temperature Coefficient	$I_D = 250 \mu\text{A}$, Referenced to 25°C		-4.1		$\text{mV}/^\circ\text{C}$
$R_{DS(on)}$	Static Drain–Source On–Resistance	$V_{GS} = 4.5 \text{ V}$, $I_D = 25\text{A}$ $V_{GS} = 10 \text{ V}$, $I_D = 25\text{A}$ $V_{GS} = 4.5 \text{ V}$, $I_D = 25\text{A}$, $T_J=125^\circ\text{C}$		6.2 5.5 9.6	9 7.5 16	$\text{m}\Omega$
$I_{D(on)}$	On–State Drain Current	$V_{GS} = 4.5 \text{ V}$, $V_{DS} = 10 \text{ V}$	60			A
g_{FS}	Forward Transconductance	$V_{DS} = 5\text{V}$, $I_D = 25 \text{ A}$		117		S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = 15 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1.0 \text{ MHz}$		2418		pF
C_{oss}	Output Capacitance			549		pF
C_{rss}	Reverse Transfer Capacitance			243		pF
Switching Characteristics (Note 2)						
$t_{d(on)}$	Turn–On Delay Time	$V_{DD} = 15 \text{ V}$, $I_D = 1 \text{ A}$, $V_{GS} = 4.5 \text{ V}$, $R_{\text{GEN}} = 6 \Omega$		21	34	ns
t_r	Turn–On Rise Time			20	32	ns
$t_{d(off)}$	Turn–Off Delay Time			60	96	ns
t_f	Turn–Off Fall Time			30	48	ns
Q_g	Total Gate Charge	$V_{DS} = 15 \text{ V}$, $I_D = 50 \text{ A}$, $V_{GS} = 4.5 \text{ V}$		32	51	nC
Q_{gs}	Gate–Source Charge			10		nC
Q_{gd}	Gate–Drain Charge			9		nC
Drain–Source Diode Characteristics and Maximum Ratings						
I_s	Maximum Continuous Drain–Source Diode Forward Current			50		A
V_{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}$, $I_s = 25 \text{ A}$ (Note 2)		0.8	1.3	V

Notes:

1. Maximum continuous current is limited by the package.
2. Pulse Test: Pulse Width < 300μs, Duty Cycle < 2.0%

Typical Characteristics

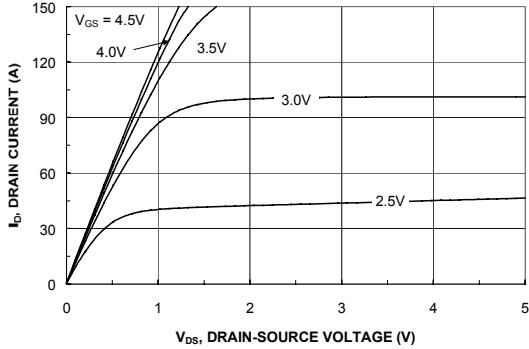


Figure 1. On-Region Characteristics.

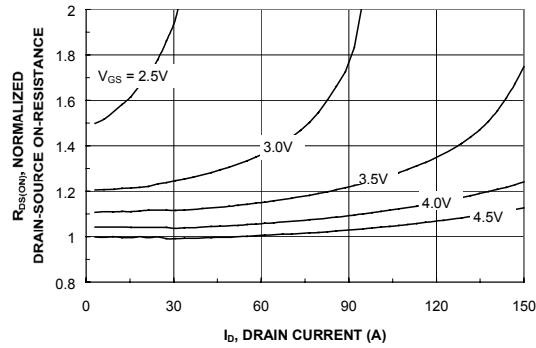


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

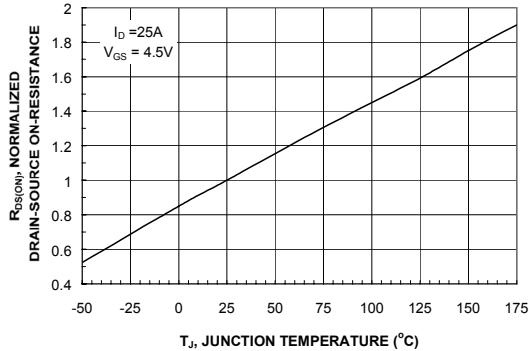


Figure 3. On-Resistance Variation with Temperature.

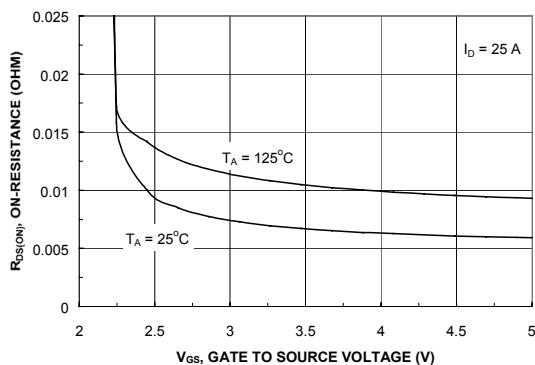


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

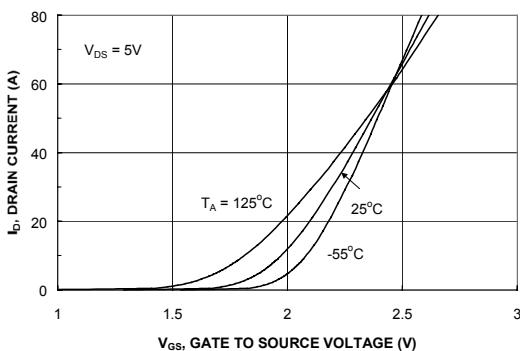


Figure 5. Transfer Characteristics.

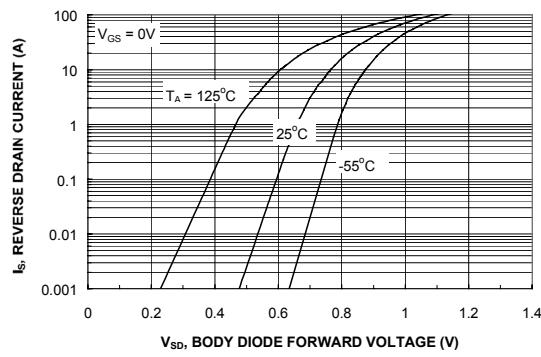


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.